



40V P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(ON)}	I _D T _C = +25°C
40\/	45mΩ @ V _{GS} = -10V	-20A
-40V	55mΩ @ V _{GS} = -4.5V	-18A

Description

This MOSFET has been designed to minimize the on-state resistance ($R_{DS(ON)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- Backlighting
- DC-DC Converters
- Power Management Functions

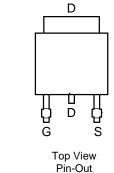
Features

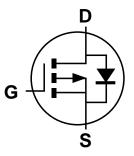
- 100% Unclamped Inductive Switch (UIS) Test in Production
- Low On-resistance
- Fast Switching Speed
- Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

- Case: TO252
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish Annealed over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208 ³
- Weight: 0.33 grams (Approximate)







Equivalent Circuit

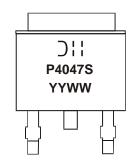
Ordering Information (Note 4)

Product	Case	Packaging
DMP4047SK3-13	TO252	2,500/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



J!! = Manufacturer's Marking
P4047S = Product Type Marking Code
YYWW = Date Code Marking
YY = Year (ex: 15 = 2015)
WW = Week (01 to 53)



Characteristic	Symbol	Value	Unit
Drain-Source Voltage	V _{DSS}	-40	V
Gate-Source Voltage	V _{GSS}	±20	V
Continuous Drain Current (Note 6) V _{GS} = -10V	I _D	-20 -12.7	А
Maximum Body Diode Continuous Current	Is	-2.5	Α
Pulsed Drain Current (10µs pulse, Duty Cycle = 1%)	I _{DM}	-40	Α
Avalanche Current (Note 7) L = 0.1mH	I _{AS}	-18	Α
Avalanche Energy (Note 7) L = 0.1mH	E _{AS}	16	mJ

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Total Dawar Dissination (Note 5)	$T_A = +25^{\circ}C$	D	1.6	W
Total Power Dissipation (Note 5)	$T_A = +70^{\circ}C$	P_{D}	1.0	
Thormal Bosistanae, Jungtion to Ambient (Note 5)	Steady state	D- · ·	77	°C/W
Thermal Resistance, Junction to Ambient (Note 5)	t<10s	$R_{\theta JA}$	34	
Total Power Dissipation (Note 6)	$T_A = +25^{\circ}C$	Б	2.7	W
Total Fower Dissipation (Note o)	$T_A = +70^{\circ}C$	P_{D}	1.7	
Thermal Resistance, Junction to Ambient (Note 6)	Steady state	Ъ	47	°C/W
Thermal Resistance, Junction to Ambient (Note 6)	t<10s	$R_{\theta JA}$	30	
Thermal Resistance, Junction to Case (Note 6)	$R_{ heta JC}$	4.8		
Operating and Storage Temperature Range		$T_{J_i} T_{STG}$	-55 to +150	°C

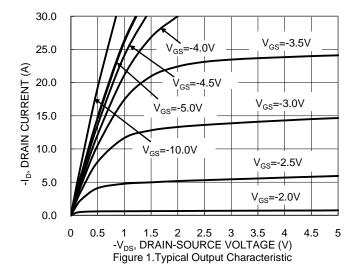
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

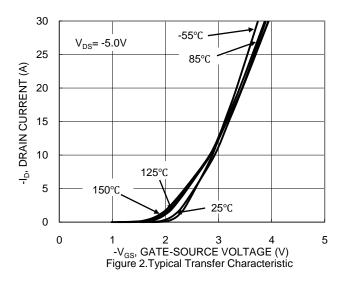
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BV _{DSS}	-40	-	-	V	$V_{GS} = 0V, I_D = -250\mu A$	
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}	-	-	-1	μA	$V_{DS} = -40V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	-	-	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	V _{GS(TH)}	-1.0	1	-3.0	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	
Static Drain-Source On-Resistance	D		33	45	mΩ	$V_{GS} = -10V, I_D = -4.4A$	
Static Drain-Source On-Resistance	R _{DS(ON)}	_	40	55	11122	$V_{GS} = -4.5V$, $I_D = -3.7A$	
Diode Forward Voltage	V _{SD}	-	-0.75	-1.2	V	$V_{GS} = 0V, I_S = -3.9A$	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	Ciss	_	1328	-	pF	\\ 20\\ \\ 0\\	
Output Capacitance	Coss	=	103	-	pF	$V_{DS} = -20V, V_{GS} = 0V,$ f = 1.0MHz	
Reverse Transfer Capacitance	Crss	=	81	-	pF	11 = 1.0IVIN2	
Gate Resistance	R _G	_	7.7	-	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge (V _{GS} = -4.5V)	Qg	_	11.2	-	nC		
Total Gate Charge (V _{GS} = -10V)	Qg	-	23.2	-	nC	V _{DS} = -20V, I _D = -4.9A	
Gate-Source Charge	Qgs	-	3.3	-	nC	V _{DS} = -20V, I _D = -4.9A	
Gate-Drain Charge	Qgd	-	3.9	-	nC		
Turn-On Delay Time	t _{D(ON)}	1	18.5	-	ns		
Turn-On Rise Time	t _R	-	28.2	-	ns	$V_{DS} = -20V, I_{D} = -3.9A$	
Turn-Off Delay Time	t _{D(OFF)}	-	38.8	-	ns	$V_{GS} = 4.5V$, $R_G = 1\Omega$	
Turn-Off Fall Time	t _F	_	28.6	_	ns		
Body Diode Reverse Recovery Time	t _{RR}	-	15.4	-	ns	1 200 4:/4 4000/	
Body Diode Reverse Recovery Charge	Q _{RR}	-	5.4	-	nC	$I_F = -3.9A$, di/dt = 100A/ μ s	

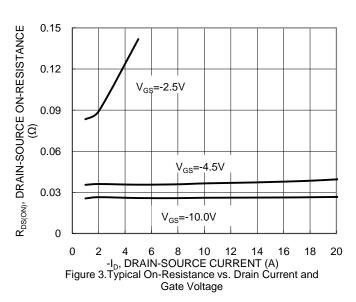
Notes:

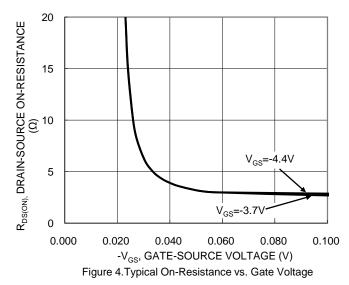
- 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
- 6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
- 7. IAs and EAs ratings are based on low frequency and duty cycles to keep T_J = +25°C.
- 8. Short duration pulse test used to minimize self-heating effect.
- 9. Guaranteed by design. Not subject to product testing.

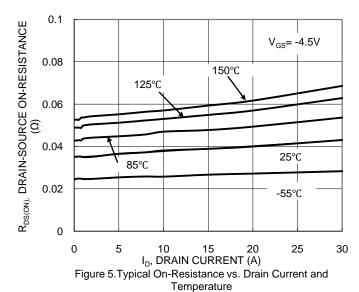












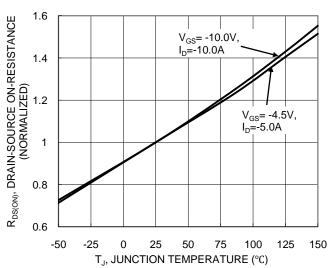


Figure 6. On-Resistance Variation with Temperature



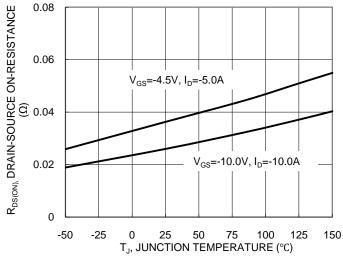


Figure 7. On-Resistance Variation with Temperature

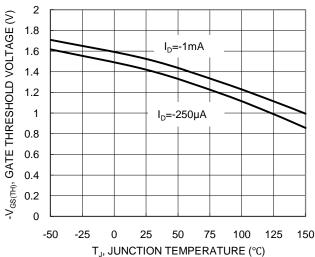
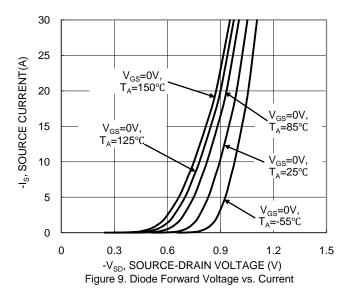


Figure 8. Gate Threshold Variation vs. Junction Temperature



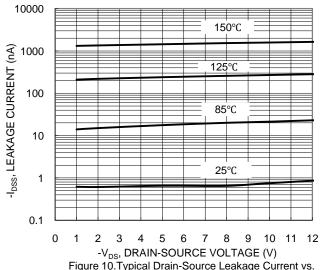
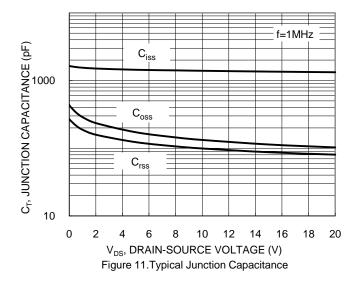
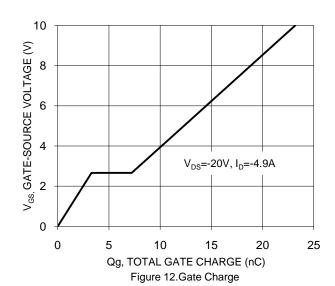
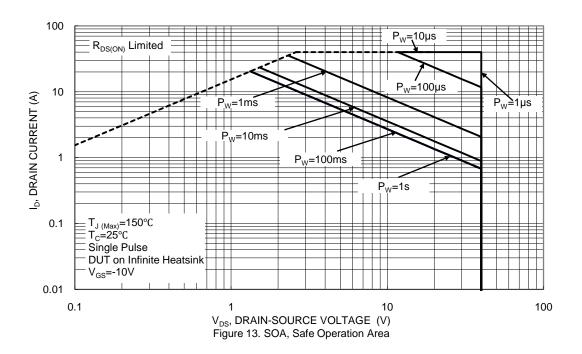


Figure 10.Typical Drain-Source Leakage Current vs. Voltage









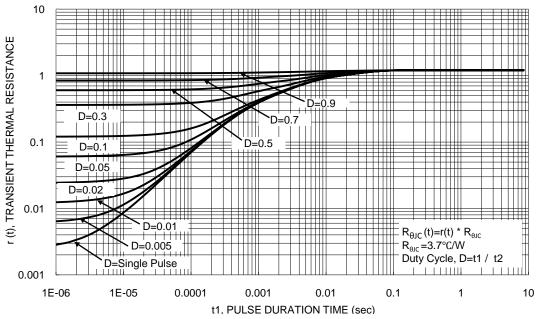
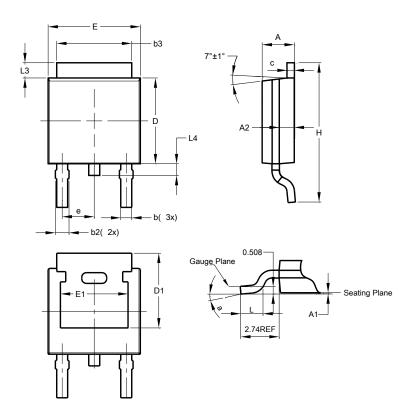


Figure 14. Transient Thermal Resistance



Package Outline Dimensions

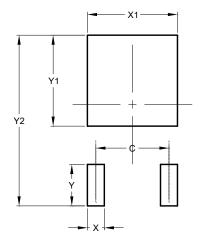
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



TO252 (DPAK)					
Dim	Min	Max	Тур		
Α	2.19	2.39	2.29		
A 1	0.00	0.13	0.08		
A2	0.97	1.17	1.07		
b	0.64	0.88	0.783		
b2	0.76	1.14	0.95		
b3	5.21	5.46	5.33		
С	0.45	0.58	0.531		
D	6.00	6.20	6.10		
D1	5.21	-	1		
е	-	-	2.286		
Е	6.45	6.70	6.58		
E1	4.32	-	1		
Н	9.40	10.41	9.91		
L	1.40	1.78	1.59		
L3	0.88	1.27	1.08		
L4	0.64	1.02	0.83		
а	0°	10°	-		
All Dimensions in mm					

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	4.572
Х	1.060
X1	5.632
Υ	2.600
Y1	5.700
Y2	10.700



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